



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2018-05-09
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	Giovanni Giacopello	Representative Title	ADG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement		
Supplier Acceptance *	true	Legal Declaration *
		Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STPS3L60S	HNZK*Z25Q81U	A	9941	2018-05-09
	Amount	UoM	Unit type	ST ECOPACK Grade
	250	mg	Each	ECOPACK® 2
Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)			

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
Bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SOJ	4.5 - 2.16 - 3.68	2	J bend	
Comment	Package: SMC CLIP (SOD 15 NEW)			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : ELV directive : 2000/53/EC amended 2017/2096 _November 2017	
Query	Response
1 - Product(s) meets EU ELV requirements without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
Exemption Id.	Description
8e	Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)

QueryList : California Prop65 list, dated 29th December 2017			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.01	Die	48
Lead	3.96	Soft solder	15848

QueryList : REACH-15th January 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
-	-			0
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material
-	-	0.00		

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	HNZK*Z25Q81U					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	1.123	mg	supplier	die	Silicon (Si)	7440-21-3		1.086	mg	967053	4344
				supplier	metallization	Aluminium (Al)	7429-90-5		0.007	mg	6233	28
				supplier	metallization	Gold (Au)	7440-57-5		0.005	mg	4452	20
				supplier	passivation	Nickel (Ni)	7440-02-0		0.005	mg	4452	20
				supplier	metallization	Titanium (Ti)	7440-32-6		0.001	mg	892	4
				supplier	metallization	Tungsten (W)	7440-33-7		0.002	mg	1781	8
				supplier	Passivation	Silicon Oxide	7631-86-9		0.007	mg	6233	28
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.001	mg	890	4
				supplier	back side metallization	Gold (Au)	7440-57-5		0.002	mg	1781	8
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.007	mg	6233	28
				Leadframe & Clip	M-004 Copper and its alloys	89.957	mg	supplier	alloy	Copper (Cu)	7440-50-8	
supplier	alloy	Iron (Fe)	7439-89-6						0.009	mg	100	36
supplier	alloy	Phosphorus metal	7723-14-0						0.030	mg	333	120
supplier	alloy	Zinc (Zn)	7440-66-6						0.004	mg	45	16
supplier	alloy	Lead (Pb)	7439-92-1					7a-Lead in high me	3.962	mg	925053	15848
Soft solder	Solder	4.283	mg	JIG - R	solder	Tin (Sn)	7440-31-5		0.215	mg	50198	860
				supplier	solder	Silver (Ag)	7440-22-4		0.106	mg	24749	424
				supplier	solder	Amorphous Silica	7631-86-9		93.632	mg	614000	374528
Encapsulation	M-011 Other inorganic materials	152.495	mg	supplier	mold compound	Quartz	14808-60-7		30.500	mg	200007	122000
				supplier	mold compound	epoxy resin	25068-38-6		18.298	mg	119991	73192
				supplier	mold compound	phenolic resin	29690-82-2		9.150	mg	60002	36600
				supplier	mold compound	Carbon black	1333-86-4		0.915	mg	6000	3660
				supplier	solder alloy	Tin (Sn)	7440-31-5		2.142	mg	1000000	8568
connections coating	Solder	2.142	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		2.142	mg	1000000	8568